

## **MP45DT01**

# MEMS audio sensor omni-directional digital microphone

Preliminary data

#### **Features**

- Single supply voltage operation
- Low power consumption
- 120 dBSPL acoustic overload point
- Omni-directional sensitivity
- PDM single-bit output with stereo operation support
- HLGA package
- ECOPACK® RoHS and "Green" compliant

#### **Applications**

- Mobile terminals
- Laptop and notebook computers
- Portable media players
- VolP
- Speech recognition
- A/V eLearning devices
- Gaming and virtual reality input devices
- Digital still and video cameras
- Antitheft systems

## **Description**

The MP45DT01 is a compact low-power microphone built up with a sensing element and an IC interface with stereo operation capability.

The sensing element, capable of detecting acoustic waves, is manufactured using a



specialized silicon micromachining process to produce audio sensors.

The IC interface is manufactured using a CMOS process that allows to design a dedicated circuit able to provide a digital signal to the external world in PDM format.

The MP45DT01 has an acoustic overload point of 120 dBSPL with 58 dB signal to noise ratio.

The MP45DT01 is available in SMD compliant package and it is guaranteed to operate over an extended temperature range from -30 °C to +85 °C.

Table 1. Device summary

Order code	Temperature range [°C]	Package	Packing
MP45DT01	-30 to +85	HLGA 4.72x3.76 6LD	Tray
MP45DT01TR	-30 to +85	HLGA 4.72x3.76 6LD	Tape and reel

MP45DT01

## **Contents**

Acou	ustic and electrical specifications	4
2.1	Acoustic and electrical characteristics	4
2.2	Absolute maximum ratings	5
2.3	Frequency response	
Fund	ctionality	). 6
3.1	L/R channel selection	6
Appl	lication hints	7
4.1	Soldering information	8
Pack	age information	9
Revi	sion history	. 10
lete.	Product(s)	
	2.1 2.2 2.3 Fund 3.1 Appl 4.1 Pack	2.2 Absolute maximum ratings 2.3 Frequency response  Functionality 3.1 L/R channel selection  Application hints 4.1 Soldering information  Package information

MP45DT01 Pin description

# 1 Pin description

Figure 1. Pin connection

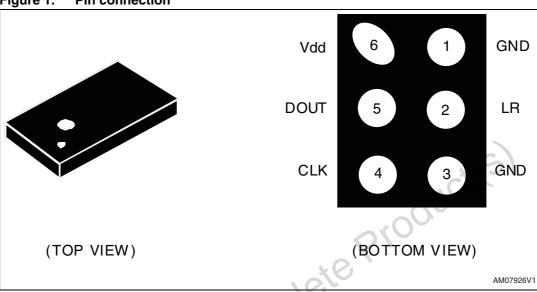


Table 2. Pin description

	Pin #	Pin name	Function
	1	GND	0 V supply
	2	LR	Left/right channel selection; MIC1 LR connected to GND/Vdd and MIC2 LR connected to Vdd/GND (see <i>Figure 3</i> )
	3	GND	0 V supply
	4	CLK	Syncronization input clock
	5	DOUT	Left/Right PDM data output
10	6	Vdd	Power supply
Opson			

# 2 Acoustic and electrical specifications

#### 2.1 Acoustic and electrical characteristics

Characteristics @ Vdd = 1.8 V, Clock = 2.4 MHz, T = 25 °C unless otherwise noted.

Table 3. Electrical characteristics

Symbo I	Parameter	Test condition	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Vdd	Supply voltage		1.64	1.8	3.6	V
ldd	Current consumption in normal mode	No load on data line		0.65	.(0	mA
IddPdn	Current consumption in power-down mode <sup>(2)</sup>			20	7 <sub>C/</sub>	μΑ
Scc	Short circuit current		1		10	mA
AOP	Acoustic overload point		P	120		dBSP L
So	Sensitivity	\ C	10	-26		dBFS
SNR	Signal to noise ratio	A-weighted @1 kHz, 1Pa		58		dB
PSR	Power supply rejection	guaranteed by design <sup>(3)</sup>		-70		dBFS
Clock	Input clock frequency <sup>(4)</sup>		1	2.4	3.25	MHz
TWK	Wake up time <sup>(5)</sup>	guaranteed by design			10	ms
Тор	Operating temperature range		-30		+85	°C

- 1. Typical specifications are not guaranteed.
- 2. Input clock in static mode.
- 3. Test signal: 217Hz square wave, 100 mVpp on Vdd pin.
- 4. Duty cycle: min=40% max=60%.
- 5. Time from the first clock edge to valid output data.

Table 4. Distorsion specifications

Parameter	Test condition	Value
Distorsion	100 dBSPL (50Hz - 4kHz)	<1 % THD + N
Distorsion	115 dBSPL (1kHz)	<5 % THD + N

## 2.2 Absolute maximum ratings

Stresses above those listed as "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5. Absolute maximum ratings

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.3 to 6	V
Vin	Input voltage on any control pin	-0.3 to Vdd +0.3	V
T <sub>STG</sub>	Storage temperature range	-40 to +125	°C
ESD	Electrostatic discharge protection	2(HBM)	kV



This is a mechanical shock sensitive device, improper handling can cause permanent damages to the part



This is an ESD sensitive device, improper handling can cause permanent damages to the part

## 2.3 Frequency response

Table 6. Frequency Response Mask for digital microphones (1)

Frequency / Hz	<b>S</b> Lower limit	Upper limit	Unit
20100	-5	+5	dBr 1kHz
1008000	-2	+2	dBr 1kHz
800010000	-5	+5	dBr 1kHz

1. @ T=20°C and acoustic stimulus =1Pa (94dB SPL)

Functionality MP45DT01

## 3 Functionality

#### 3.1 L/R channel selection

The L/R digital pad lets the user select the DATA signal pattern as explained in *Table* . L/R pin must be connected to Vdd or GND.

Table 7. L/R channel selection

L/R	CLK Low	CLK High
GND	Data Valid	High Impedence
Vdd	High Impedence	Data Valid
Obsolete Productl	High Impedence	Producite

MP45DT01 Application hints

## 4 Application hints

Figure 2. MP45DT01 electrical connection

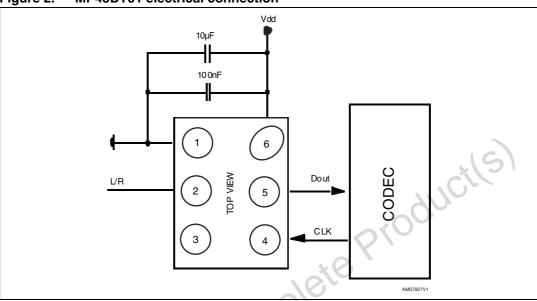
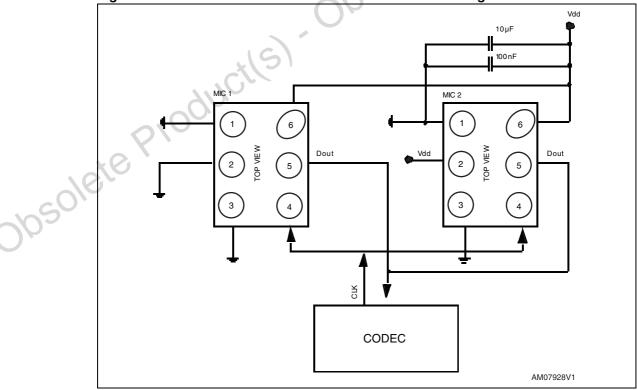


Figure 3. MP45DT01 electrical connection for stereo configuration



Power supply decoupling capacitors (100 nF ceramic, 10  $\mu$ F ceramic) should be placed as near as possible to the pin 6 of the device (common design practice).

L/R pin must be connected to Vdd or GND (refer to Table 2).

Application hints MP45DT01

## 4.1 Soldering information

The HLGA 4.72x3.76 6LD package is compliant with the ECOPACK<sup>®</sup>, RoHS and "Green" standard. It is qualified for soldering heat resistance according to JEDEC J-STD-020. Land pattern and soldering recommendations are available at <a href="https://www.st.com">www.st.com</a>.



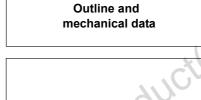
MP45DT01 Package information

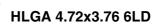
## 5 Package information

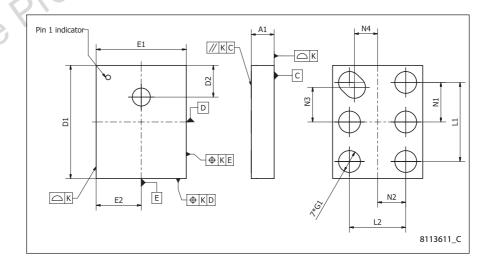
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Figure 4. HLGA 4.72x3.76 6LD: mechanical data and package dimensions

Dimensions			
Ref.	mm		
	Min.	Тур.	Max.
A1	0.900	1.0	1.10
D1	4.620	4.720	4.820
D2	1.070	1.320	1.570
R1	0.740	0.840	0.940
E1	3.620	3.760	3.820
E2	1.630	1.880	2.130
L1	3.150	3.300	3.450
L2	2.200	2.350	2.500
N1	1.500	1.650	1.800
N2	1.025	1.175	1.325
N3	1.300	1.450	1.600
N4	0.815	0.965	1.115
G1	0.760	0.910	1.160
K	. (	0.050	







Revision history MP45DT01

# 6 Revision history

Table 8. Document revision history

Date	Revision	Changes
06-Aug-2010	1	First release.



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